

559/560 Series

Fuse Blocks for TE5/TR5 Type Fuses



559 Series Holder

560 Series Holder

Product Characteristics

	559 Series (Lead Free)	560 Series
Compatible Fuses	TR5/TE5	TR5/TE5
Materials	Holder: Black Thermoplastic, UL94 V-0 Metal Parts: Copper alloy; solderable tinned	Holder: Thermoplastic, UL 94 V-0 Metal Parts: Copper alloy; solderable tinned
Electrical Data (23°C)	Rated Voltage: 250V Max. Current/Power: 6.3 A /1.6 W	
Mounting	PC Board, 7.18 mm pin spacing	PC Board, 5.08 mm pin spacing
Solderability	max. 260 °C, 10 s (Wave)	
Minimum Cross Section	Conducting path - 0.1 mm ²	
Unit Weight	0.63 g	0.4 g
Ambient Temperature	-40 °C to +85 °C	

Additional Information



Resources
559 Series



Accessories
559 Series



Samples
559 Series



Resources
560 Series



Accessories
560 Series



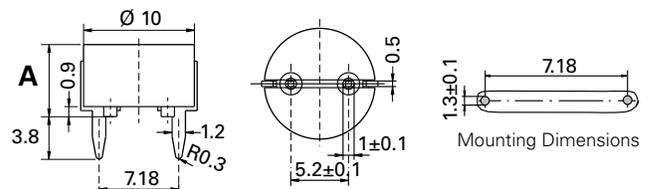
Samples
560 Series

Ordering Information

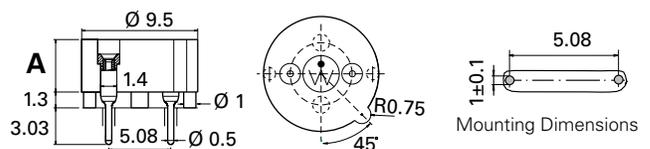
Ordering Number	"A" Height Options	Packaging
55900000001	6.5 mm (code 0001)	1000 Pcs Bulk
56000001319	3.0 mm (code 1319)	1000 Pcs Bulk
56000001009	4.3 mm (code 1009)	500 Pcs Bulk
56000001019	4.3 mm (code 1019)	1000 Pcs Bulk

Dimensions (Units in mm)

559 Series



560 Series



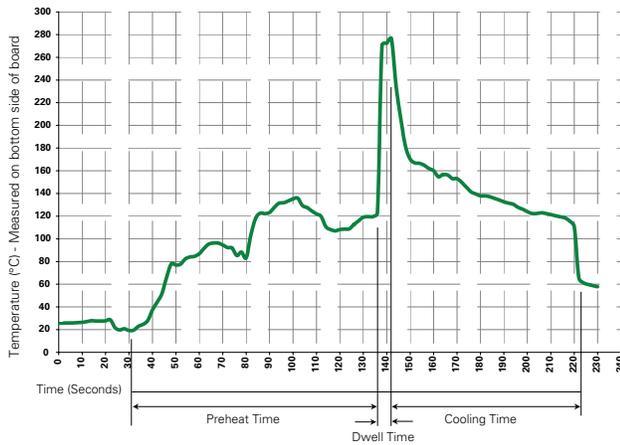
Agency Approvals

Agency	Agency File Number	
	559 Series	560 Series
	N/A	40041024
	N/A	E14721

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Soldering Parameters - Wave Soldering



Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)
Temperature Minimum:	100° C
Temperature Maximum:	150° C
Preheat Time:	60-180 seconds
Solder Pot Temperature:	260° C Maximum
Solder Dwell Time:	2-5 seconds

Recommended Hand-Solder Parameters:

Solder Iron Temperature: 350° C +/- 5° C

Heating Time: 5 seconds max.

Note: These devices are not recommended for IR or Convection Reflow process.